REV A --- SMI S256E -- SEPTEMBER 1984 --- REVISED JANUARY 1991

This Data Sheet is Applicable to All TMS27C256s and TMS27PC256s Symbolized with Code "B" as Described on Page 7-25.

- Organization . . . 32K × 8
- Single 5-V Power Supply
- Pin Compatible With Existing 256K MOS ROMs, PROMs, and EPROMs
- All Inputs/Outputs Fully TTL Compatible
- Max Access/Min Cycle Time

V <sub>CC</sub> ± 10%	
'27C/PC256-10	100 ns
'27C/PC256-12	120 ns
'27C/PC256-15	150 ns
'27C/PC256-17	170 ns
'27C/PC256-20	200 ns
'27C/PC256-25	250 ns
	27C/PC256-10 27C/PC256-12 27C/PC256-15 27C/PC256-17 27C/PC256-20

- Power Saving-CMOS Technology
- Very High-Speed SNAP! Pulse Programming
- 3-State Output Buffers
- 400-mV Minimum DC Noise Immunity With Standard TTL Loads
- Latchup Immunity of 250 mA on All Input and Output Lines
- Low Power Dissipation (V<sub>CC</sub> = 5.5 V)
  - Active . . . 165 mW Worst Case
  - Standby . . . 1.4 mW Worst Case (CMOS Input Levels)
- PEP4 Version Available With 168 Hour Burn-in, and Choices of Operating Temperature Ranges
- 256K EPROM Available With MIL-STD-883C Class B High Reliability Processing (SMJ27C256)

### description

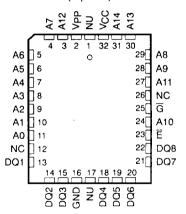
The TMS27C256 series are 262 144-bit, ultraviolet-light erasable, electrically programmable read-only memories.

The TMS27PC256 series are 262 144-bit, one-time, electrically programmable read-only memories.

#### J and N Packages (Top View)



#### FM Package (Top Vlew)



	PIN NOMENCLATURE
A0-A14	Address Inputs
Ē	Chip Enable/Powerdown
Ğ	Output Enable
GND	Ground
NC	No Internal Connection
NU	Make No External Connection
DQ1-DQ8	Inputs (programming)/Outputs
Vcc	5-V Power Supply
VPP	13 V Programming Power Supply

Texas VI

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These devices are fabricated using power-saving CMOS technology for high speed and simple interface with MOS and bipolar circuits. All inputs (including program data inputs) can be driven by Series 74 TTL circuits without the use of external pull-up resistors. Each output can drive one Series 74 TTL circuit without external resistors.

The data outputs are three-state for connecting multiple devices to a common bus. The TMS27C256 and the TMS27PC256 are pin compatible with 28-pin 256K MOS ROMs, PROMs, and EPROMs.

The TMS27C256 EPROM is offered in a dual-in-line ceramic package (J suffix) designed for insertion in mounting hole rows on 15,2-mm (600-mil) centers. The TMS27PC256 OTP PROM is offered in a dual-in-line plastic package (N suffix) designed for insertion in mounting hole rows on 15,2-mm (600-mil) centers. The TMS27PC256 OTP PROM is also supplied in a 32-lead plastic leaded chip carrier package using 1,25-mm (50-mil) lead spacing (FM suffix).

The TMS27C256 and TMS27PC256 are offered with two choices of temperature ranges of 0°C to 70°C and – 40°C to 85°C (TMS27C256-\_\_JL and TMS27C256-\_\_JE; TMS27PC256-\_\_NL and TMS27PC256-\_\_NE; TMS27PC256-\_\_FML and TMS27PC256-\_\_FME, respectively). The TMS27C256 and the TMS27PC256 are also offered with 168-hour burn-in on both temperature ranges (TMS27C256-\_\_JL4 and TMS27C256-\_\_JE4; TMS27PC256-\_\_FML4 and TMS27PC256-\_\_FME4, respectively); see table below.

All package styles conform to JEDEC standards.

EPROM AND OTP	TEMPERAT	OPERATING JRE RANGES EP4 BURN-IN	168 HR.	OR PEP4 BURN-IN TURE RANGES
PROM	0°C TO 70°C	- 40°C TO 85°C	0°C TO 70°C	- 40°C TO 85°C
TMS27C256-XXX	JL	JE	JL4	JE4
TMS27PC256-XXX	NL	NE	NL4	NE4
TMS27PC256-XXX	FML	FME	FML4	FME4

These EPROMs and OTP PROMs operate from a single 5-V supply (in the read mode), thus are ideal for use in microprocessor-based systems. One other 13-V supply is needed for programming . All programming signals are TTL level. These devices are programmable by the SNAP! Pulse programming algorithm. The SNAP! Pulse programming algorithm uses a  $V_{PP}$  of 13-V and a  $V_{CC}$  of 6.5-V for a nominal programming time of four seconds. For programming outside the system, existing EPROM programmers can be used. Locations may be programmed singly, in blocks, or at random.

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#### operation

There are seven modes of operation listed in the following table. The read mode requires a single 5-V supply. All inputs are TTL level except for  $V_{PP}$  during programming (13-V for SNAP! Pulse) and 12-V on A9 for signature mode.

				MODE	E			
FUNCTION	READ	OUTPUT DISABLE	STANDBY	PROGRAMMING	VERIFY	PROGRAM INHIBIT		TURE DE
Ē	VIL	VIL	ViH	VIL	VIH	VIН	V	IL
G	VIL	VIH	χţ	VIH	V <sub>IL</sub>	VIH	V	IL
Vpp	Vcc	Vcc	Vcc	Vpp	Vpp	Vpp	۷ر	cc
Vcc	Vcc	Vcc	Vcc	V <sub>CC</sub>	Vcc	Vcc	v <sub>c</sub>	cc
A9	×	X	X	×	X	X	v <sub>H</sub> ‡	v <sub>H</sub> ‡
A0	X	Х	Х	X	Х	×	VIL	V <sub>IH</sub>
							co	DE
DQ1-DQ8	Data Out	HI-Z	HI-Z	Data In	Data Out	HI-Z	MFG	DEVICE
							97	04

TX can be VIL or VIH.

### read/output disable

When the outputs of two or more TMS27C256s or TMS27PC256s are connected in parallel on the same bus, the output of any particular device in the circuit can be read with no interference from the competing outputs of the other devices. To read the output of a single device, a low-level signal is applied to the  $\overline{E}$  and  $\overline{G}$  pins. All other devices in the circuit should have their outputs disabled by applying a high-level signal to one of these pins. Output data is accessed at pins DQ1 through DQ8.

### latchup immunity

Latchup immunity on the TMS27C256 and TMS27PC256 is a minimum of 250 mA on all inputs and outputs. This feature provides latchup immunity beyond any potential transients at the P.C. board level when the devices are interfaced to industry-standard TTL or MOS logic devices. Input-output layout approach controls latchup without compromising performance or packing density.

For more information see application report SMLA001, "Design Considerations; Latchup Immunity of the HVCMOS EPROM Family", available through TI Sales Offices.

#### power down

Active  $I_{CC}$  supply current can be reduced from 30 mA to 500  $\mu$ A (TTL-level inputs) or 250  $\mu$ A (CMOS-level inputs) by applying a high TTL or CMOS signal to the  $\overline{E}$  pin. In this mode all outputs are in the high-impedance state.

#### erasure (TMS27C256)

Before programming, the TMS27C256 EPROM is erased by exposing the chip through the transparent lid to a high intensity ultraviolet light (wavelength 2537 Å). EPROM erasure before programming is necessary to assure that all bits are in the logic high state. Logic lows are programmed into the desired locations. A programmed logic low can be erased only by ultraviolet light. The recommended minimum exposure dose (UV intensity × exposure time) is 15-W•s/cm². A typical 12-mW/cm², filterless UV lamp will erase the device in 21 minutes. The lamp should be located about 2.5 cm above the chip during erasure. It should be noted that normal ambient light contains the correct wavelength for erasure. Therefore, when using the TMS27C256, the window should be covered with an opaque label.



<sup>‡</sup> V<sub>H</sub> = 12 V ± 0.5 V.

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### initializing (TMS27PC256)

The one-time programmable TMS27PC256 PROM is provided with all bits in the logic high state, then logic lows are programmed into the desired locations. Logic lows programmed into an OTP PROM cannot be erased.

#### SNAP! Pulse programming

The 256K EPROM and OTP PROM are programmed using the TI SNAP! Pulse programming algorithm illustrated by the flowchart in Figure 1, which programs in a nominal time of four seconds. Actual programming time will vary as a function of the programmer used.

Data is presented in parallel (eight bits) on pins DQ1 to DQ8. Once addresses and data are stable,  $\overline{E}$  is pulsed.

The SNAP! Pulse programming algorithm uses initial pulses of 100 microseconds ( $\mu$ s) followed by a byte verification to determine when the addressed byte has been successfully programmed. Up to 10 (ten) 100- $\mu$ s pulses per byte are provided before a failure is recognized.

The programming mode is achieved when  $V_{PP}=13$  V,  $V_{CC}=6.5$  V,  $\overline{G}=V_{IH}$ , and  $\overline{E}=V_{IL}$ . More than one device can be programmed when the devices are connected in parallel. Locations can be programmed in any order. When the SNAP! Pulse programming routine is complete, all bits are verified with  $V_{CC}=V_{PP}=5$  V.

## program inhibit

Programming may be inhibited by maintaining a high level inputs on the  $\overline{E}$  and  $\overline{G}$  pins.

### program verify

Programmed bits may be verified with  $V_{PP} = 13 \text{ V}$  when  $\overline{G} = V_{II}$  and  $\overline{E} = V_{IH}$ .

#### signature mode

The signature mode provides access to a binary code identifying the manufacturer and type. This mode is activated when A9 is forced to 12 V  $\pm$  0.5 V. Two identifier bytes are accessed by A0; i.e., A0 =  $V_{IL}$  accesses the manufacturer code, which is output on DQ1-DQ8; A0 =  $V_{IL}$  accesses the device code, which is output on DQ1-DQ8. All other addresses must be held at  $V_{IL}$ . Each byte possesses odd parity on bit DQ8. The manufacturer code for these devices is 97, and the device code is 04.

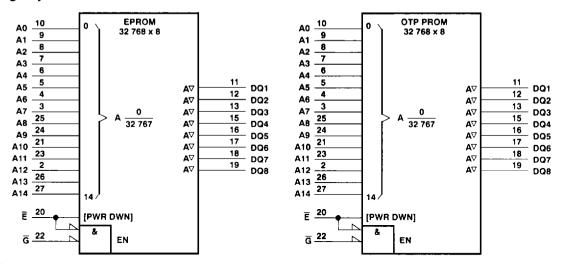
REV A - SMLS256E -- SEPTEMBER 1984 -- REVISED JANUARY 1991 Start Address = First Location Program Mode VCC = 6.5 V, Vpp = 13 V Program One Pulse = t<sub>w</sub> = 100 μs Increment Address No Last Address? Yes Address = First Location X = 0 Program One Pulse = t<sub>w</sub> = 100 μs No Fall Increment Verify X = 10? X = X + 1 Address One Byte Interactive Mode Pass No Last Address? Yes Device Falled VCC = Vpp = 5 V ±10% Compare All Bytes Fail Final Verification To Original Data Pass **Device Passed** 

Figure 1. SNAP! Pulse Programming Flowchart



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### logic symbol†



<sup>&</sup>lt;sup>†</sup> These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for J and N packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub> (see Note 1)	– 0.6 V to 7 V
Supply voltage range, V <sub>PP</sub>	– 0.6 V to 14 V
Input voltage range (see Note 1); All inputs except A9	0.6 V to 6.5 V
A9	- 0.6 V to 13.5 V
Output voltage range (see Note 1) – C	0.6 V to V <sub>CC</sub> + 1 V
Operating free-air temperature range ('27C256JL and JL4, '27PC256NL, NL4, FML	•1
and FML4)	0° C to 70°C
Operating free-air temperature range ('27C256JE and JE4, '27PC256NE, NE4, FM	E,
and FME4)	40° C to 85°C
Storage temperature range	65°C to 150°C

<sup>&</sup>lt;sup>‡</sup> Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "Recommended Operating Conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

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## recommended operating conditions

				TMS2 TMS2 TMS2 TMS2	7C/PC2 7C/PC2 7C/PC2 7C/PC2 7C/PC2 7C/PC2	56-120 56-150 56-1 56-2	TMS2 TMS2 TMS2 TMS2	27C/PC2 27C/PC2 27C/PC2 27C/PC2 27C/PC2 27C/PC2	56-12 56-15 56-17 56-20	UNIT
				MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	Read mo	de (see Note 2)	4.75	5	5.25	4.5	5	5.5	V
-		SNAP! P	ulse programming algorithm	6.25	6.5	6.75	6.25	6.5	6.75	
Vpp	Supply voltage	Read mo	de (see Note 3)	VCC - 0.6		V <sub>CC+0</sub> 6	V <sub>C</sub> C 0.6		V <sub>CC</sub> +0.6	>
		SNAP! P	ulse programming algorithm	12.75	13	13.25	12.75	13	13.25	·
ViH	High-level input v	oltage	ΠL	2		V <sub>CC</sub> +1	2		VCC+1	· ·
,,,,	J		CMOS	V <sub>CC</sub> 0.2		V <sub>CC</sub> +1	V <sub>CC</sub> 0.2		V <sub>CC</sub> +1	
VIL	Low-level input vo	oltage	TTL	0.5		0.8	- 0.5		0.8	V
			CMOS	0.5		0.2	0.5		0.2	
ТА	Operating free-ai temperature	ir	'27C256JL, JL4 '27PC256NL, NL4, FML, FML4	0		70	0		70	ç
TA	Operating free-ai temperature	ir	'27C256 JE, JE4 '27PC256 NE, NE4, FME, FME4	40		85	40		85	Ç

NOTES: 2. VCC must be applied before or at the same time as Vpp and removed after or at the same time as Vpp. The device must not be inserted into or removed from the board when Vpp or VCC is applied.

### electrical characteristics over full ranges of operating conditions

	PARAMETE	R	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Vон	High-level output voltage	High-level output voltage		3.5			v
. 011	g		!OH = 20 μA	V <sub>CC</sub> - 0.1			-
VOL	Low-level output voltage	-1	I <sub>OL</sub> = 2.1 mA			0.4	V
·OL	2011 1010 201put 1011ago		1 <sub>OL</sub> = 20 μA			0.1	•
Ιį	Input current (leakage)		V <sub>1</sub> = 0 to 5.5 V			±1	μΑ
Ю	Output current (leakage)		VO = 0 to VCC			±1	μΑ
IPP1	Vpp supply current		Vpp = V <sub>CC</sub> = 5.5 V		1	10	μΑ
IPP2	Vpp supply current (during prog	gram pulse)	Vpp = 13 V		35	50	mA
1	)	TTL-input level	V <sub>CC</sub> = 5.5 V, Ē = V <sub>IH</sub>		250	500	
CC1	VCC supply current (standby)	CMOS-input level	V <sub>CC</sub> = 5.5 V, E = V <sub>CC</sub>		100	250	μА
ICC2	V <sub>CC</sub> supply current (active)		VCC = 5.5 V, E = V <sub>IL</sub> , t <sub>cycle</sub> = minimum cycle time, outputs open		15	30	mA

<sup>&</sup>lt;sup>†</sup>Typical values are at T<sub>A</sub> = 25°C and nominal voltages.

# capacitance over recommended ranges of supply voltage and operating free-air temperature, $f = 1 \text{ MHz}^{\ddagger}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Ci	Input capacitance	V <sub>I</sub> = 0, f = 1 MHz		6	10	ρF
CO	Output capacitance	V <sub>O</sub> = 0, f = 1 MHz		10	14	pF

<sup>&</sup>lt;sup>†</sup>Typical values are at T<sub>A</sub> = 25°C and nominal voltages.

<sup>&</sup>lt;sup>‡</sup> Capacitance measurements are made on a sample basis only



<sup>3.</sup> Vpp can be connected to VCC directly (except in the program mode). VCC supply current in this case would be ICC + Ipp.

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# switching characteristics over full ranges of recommended operating conditions (see Notes 4 and 5)

	PARAMETER	TEST CONDITIONS (see Notes 4 and 5)	'27PC	256-100 256-100 256-10 256-10	27PC	56-120 256-120 56-12 256-12	'27PC	56-150 256-150 256-15 256-15	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	]
ta(A)	Access time from address			100		120		150	ns
ta(E)	Access time from chip enable	C <sub>L</sub> = 100 pF,		100		120		150	ns
ten(G)	Output enable time from G	1 Series 74 TTL Load,		55		55		75	ns
<sup>t</sup> dis	Output disable time from $\widehat{G}$ or $\widehat{E}$ , whichever occurs first $^{\dagger}$	Input t <sub>f</sub> ≤ 20 ns, Input t <sub>f</sub> ≤ 20 ns	0	45	0	45	0	60	ns
¹v(A)	Output data valid time after change of address, $\overline{E}$ , or $\overline{G}$ , whichever occurs first $\dagger$		0		0		0		ns

	PARAMETER	TEST CONDITIONS (see Notes 4 and 5)	'27C2	256-1 256-1 256-17 256-17	'27C2	256-2 256-2 256-20 256-20			UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	1
ta(A)	Access time from address			170		200		250	ns
ta(E)	Access time from chip enable	C <sub>i</sub> = 100 pF,		170		200		250	ns
ten(G)	Output enable time from G	1 Series 74 TTL Load,	_	75		75		100	ns
<sup>t</sup> dis	Output disable time from $\overline{G}$ or $\overline{E}$ , whichever occurs first $^{\dagger}$	Input t <sub>f</sub> ≤ 20 ns, Input t <sub>f</sub> ≤ 20 ns	0	60	0	60	0	60	ns
t <sub>V</sub> (A)	Output data valid time after change of address, E, or G, whichever occurs first <sup>†</sup>		0		0		0		ns

<sup>†</sup>Value calculated from 0.5 V delta to measured level. This parameter is only sampled and not 100% tested.

# switching characteristics for programming: $V_{CC}$ = 6.50 V and $V_{PP}$ = 13 V (SNAP! Pulse), $T_A$ = 25°C (see Note 4)

	PARAMETER	MIN	NOM	MAX	UNIT
tdis(G)	Output disable time from G	0		130	ns
ten(G)	Output enable time from G			150	ns

NOTES: 4. For all switching characteristics the input pulse levels are 0.4 V to 2.4 V. Timing measurements are made at 2 V for logic high and 0.8 V for logic low). (Reference page 7-23.)

<sup>5.</sup> Common test conditions apply for the t<sub>dis</sub> except during programming.

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recommended timing requirements for programming:  $V_{CC} = 6.5 \text{ V}$  and  $V_{PP} = 13 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$  (see Note 4)

		MIN	NOM	MAX	UNIT
tw(IPGM)	Initial program pulse duration	95	100	105	μS
t <sub>su(A)</sub>	Address setup time	2			μ\$
t <sub>su(G)</sub>	G setup time	2			μS
t <sub>su(E)</sub>	E setup time	2			μS
t <sub>su(D)</sub>	Data setup time	2			μS
tsu(VPP)	Vpp setup time	2			μS
t <sub>su(VCC)</sub>	V <sub>CC</sub> setup time	2			μS
th(A)	Address hold time	0			μς
th(D)	Data hold time	2			μS

NOTE 4: For all switching characteristics the input pulse levels are 0.4 V to 2.4 V. Timing measurements are made at 2 V for logic high and 0.8 V for logic low). (Reference page 7-23.)

### PARAMETER MEASUREMENT INFORMATION

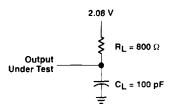
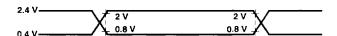


Figure 2. AC Testing Output Load Circuit

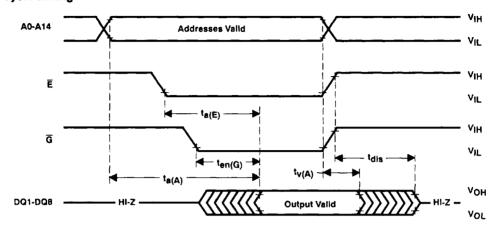
### AC testing input/output wave forms



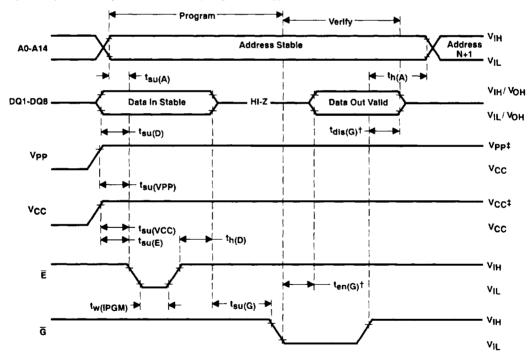
A.C. testing inputs are driven at 2.4 V for logic high and 0.4 V for logic low. Timing measurements are made at 2 V for logic high and 0.8 V for logic low for both inputs and outputs.

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### read cycle timing



## program cycle timing (SNAP! Pulse programming)



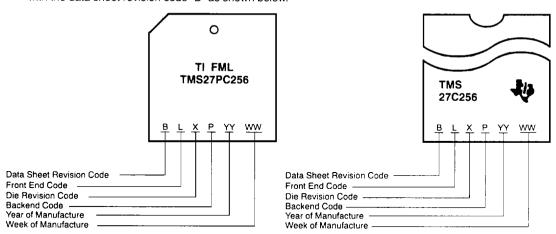
 $<sup>\</sup>dagger t_{dis(G)}$  and  $t_{en(G)}$  are characteristics of the device but must be accompdated by the programmer.

<sup>‡ 13-</sup>V Vpp and 6.5-V VCC for SNAP! Pulse programming.

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### device symbolization

This data sheet is applicable to all TI TMS27C256 CMOS EPROMs and TMS27PC256 CMOS OTP PROMS with the data sheet revision code "B" as shown below.



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### TYPICAL TMS27C/PC256 CHARACTERISTICS

